

## Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time. ([Custom Circuit Boards china](#))

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

PLEASE CLICK THESE FOR MORE INFORMATION: [led pcb board Printed circuit board](#)

## Product Description

PCB P/N	6L High TG170 pcb with BGA 8mil
Layer Count	6L
Material	FR-4 TG170
Board thk	1.60mm
copper thk	1/1/1/1/1/1oz
Smallest hole size	0.20mm
No. of holes (pcs)	683
line w/s	4/4mil
Impedance control. Y / N (Tol %)	Y
Surface Finishing	ENIG Au:0.05-0.10UM
Solder Mask Silkscreen	Green / White
Single board size	Dim X (mm):63.7; Dim Y (mm):47.1
Panelisation	Dim X (mm):143.4;Dim Y (mm):94.2;No Of UPS:4
Special:peelable mask	N
Routing/Punching	CNC

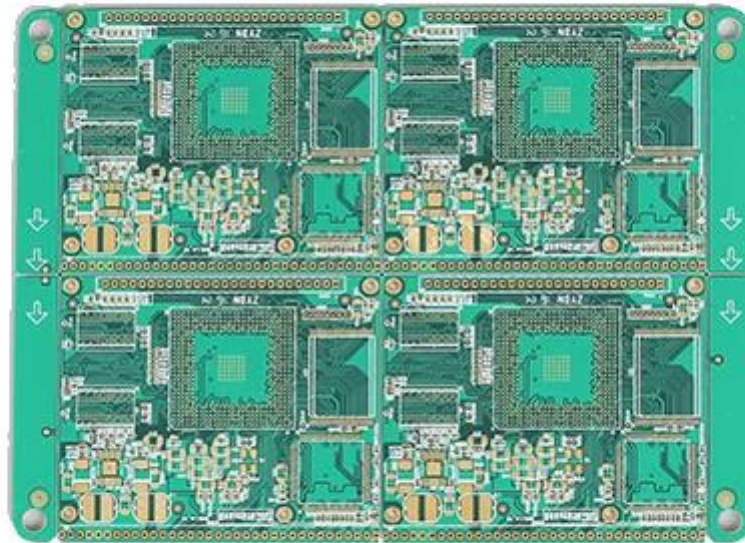
•



[www.o-leading.com](http://www.o-leading.com)



[www.o-leading.com](http://www.o-leading.com)



[www.o-leading.com](http://www.o-leading.com)

Our Team





Certifications



CICC INSPECTION CERTIFICATION



**QUALITY MANAGEMENT SYSTEM CERTIFICATE**

Certificate No.: 16118Q10347R05

**We hereby certify that**

**O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED**

Credit No.: 61691591-000-07-17-2

Registration Add: ROOM 603D 6/F HANG PONT COMMERCIAL BUILDING,31 TONKIN ST,CHEUNG SHA WAN,KL,HK

Business Add:1313 Floor 13,Fortune Building,Danshui Town,Huizhou District, Huizhou, Guangdong,China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards  
GB/T19001-2016 idt ISO9001:2015

**Scope of certification**  
Sales of printed circuit boards

Initial Issuance period: February 27, 2018  
This certificate is valid during: February 27, 2018 -- February 26, 2021  
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark
-----------------------------	----------------	------------------------------	----------------

The certification registration scope shall include those products/services scopes which fall to be covered by the relevant effective administrative permission and qualification permission required by the state. The effectiveness of this certificate shall be evaluated by annual surveillance audit of CICC. The certificate shall be valid when used together with the surveillance audit conclusion. The related information of this certification can be searched at the public website of website www.cicc.com.cn.






201726 201VZL430354 - Wiring, Printed - Component

**UL ONLINE CERTIFICATIONS DIRECTORY**

**ZPMV2.E490354**  
**Wiring, Printed - Component**

For enhanced search functionality, please visit [UL's online Family of Databases](#). Click on a product designation for complete information.

[Page Bottom](#)

**Wiring, Printed - Component**

See General Information for Wiring, Printed - Components

**O-LEADING SUPPLY CHAIN CO LIMITED**      4190354  
Fortune Building, Nanheng West Road  
Room 1313  
Huizhou, Guangdong 516211, CHINA

Cond Width			Min		Max		Max		Max		
Min	Min	Cond	SS/	Area	Solder	Dper	Flame	Flame	Flame	CT	
Edge	Edge	Thk	DS/	Diam	Limits	Temp	Class	UL796	UL796	T	
Typc	max(in)	mm(in)	mic(mil)	DS0	mm(in)	C	sec	C	Class	DSR	I
<b>Hull/Bayer (mass laminate) printed wiring boards.</b>											
<b>O-LEADING-401</b>											
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	12.7 (0.5)	260	10	130	V-0	-	-
<b>O-LEADING-407</b>											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	D5	9.2 (0.4)	260	10	130	V-0	NI	-
<b>Hull/Bayer printed wiring boards.</b>											
<b>O-LEADING-408</b>											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) mi:1.35	D6	50.8 (2.0)	260	20	130	V-0	NI	1
<b>Single layer printed wiring boards.</b>											
<b>O-LEADING-002</b>											
	0.76 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	105	V-0	NI	-
<b>O-LEADING-003</b>											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	130	V-0	▲	-
<b>O-LEADING-033</b>											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	S5	25.4 (1.0)	260	10	120	V-0	NI	-
<b>O-LEADING-205</b>											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	D6	69.6 (2.7)	260	10	130	V-0	NI	-
<b>O-LEADING-206</b>											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	D5	69.6 (2.7)	260	10	130	V-0	NI	-

\* - CT marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.  
Last updated on 2017-01-27

Questions? [Print this page](#) [Terms of Use](#) [Page Top](#)

[http://www.ul.com/onlinecertificationsdirectory/Print/ZPMV2.E490354/Wiring,Printed-Component/10](#)

**SGS**

**Test Report**      No. CANEC1805164701      Date: 03 Apr 2018      Page 2 of 8

Test Results:

Test Part Description:

**Specimen No.**      **SGS Sample ID**      **Description**  
SN1      CAN18-051647.001      Green "PCB"

Remarks:

(1) 1 mg/kg = 1 ppm = 0.0001%

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

**RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU**

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

**SGS**

Member of the SGS Group (SGL SA)

## Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer( <a href="#">oem pcb board manufacturer china</a> )
Delivery Detail	7-12days



## FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching → Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.